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(54) **LEAD FRAME FOR RESIN SEALED TYPE SEMICONDUCTOR DEVICE**

direction of tab leads 2 only.

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(57) Abstract:

PURPOSE: To avoid any tab lead deformation in case of filling resin by a method wherein, when tab leads supporting tab are projected inward from a square ring type outer frame constituting a lead frame, the bases of tab leads near outer frames are formed into flexible structure composed of bending pieces forming hollow diamond type insides to be flexible in the axial direction of tab leads only.

CONSTITUTION: A tab leads 2 supporting a tab 1 for loading semiconductor pellet are projected inward from a square ring type frame 4 constituting a lead frame while multiple leads 3 are likewise projected from the outer frame 4 to be connected to band type dams 5 making the tab leads extending therefrom radially reach the outer periphery of tab 1. In such a constitution, the bases of tab leads 2 supporting tab 1 normally composed of outer ends 6 comprising lateral pieces 7 and fine longitudinal pieces 8 forming hollow insides may be substituted by flexible structure composed of bending pieces 9 forming hollow diamond type insides to be flexible in the axial

